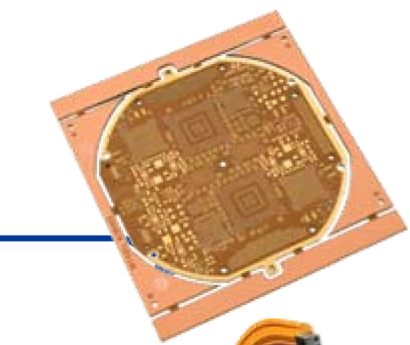

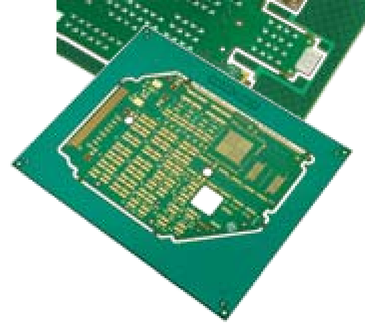

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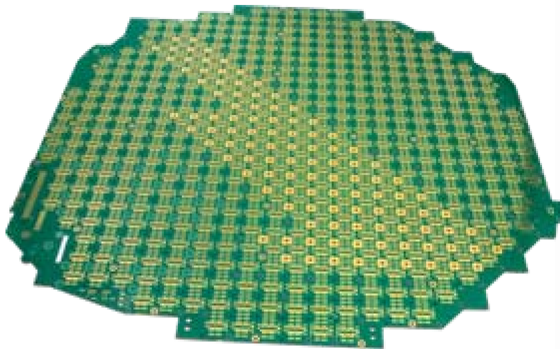

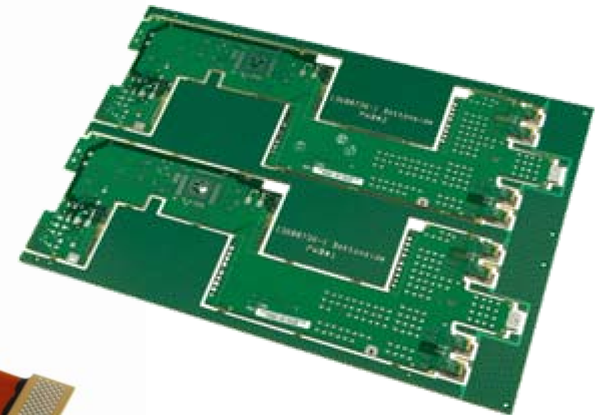

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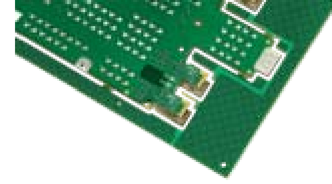
Organization Structure



- General Manager *Pam Simonds*
  - Finance *John Geraghty*
    - Accounting
    - Costing
    - IT
  - Product Engineering *Kurt Whitcomb*
    - CAM Techs
    - Product Engineers
    - Programming
    - RF Development Engineer
  - Director of Operations *Christine Marvell*
    - WC Manager Mat'l Prep-Drill
    - WC Manager C-Image–Final QC
    - WC Manager Finishing / Assembly Nogales/Nashua
    - Planning Managers Rigid/Flex
    - New Product Introduction
    - Maintenance And Facilities
  - Marketing Manager *Derek Moody*
    - CSR
    - Acct Management
    - Apps Engineering
  - Purchasing Manager *Mike Beauchesne*
  - Quality Manager *Tom Gardenour*
    - Quality Engineers
    - Lab Techs
  - HR Manager *Valerie Hartlen*
    - Security
    - HR Rep
  - E&S *Glen Charette*
  - APC Sales Manager *Mike Sullivan*
    - APC Applications Engineer
    - APC Sales

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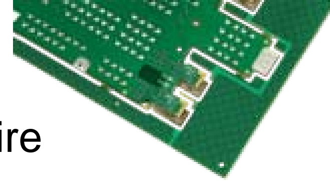
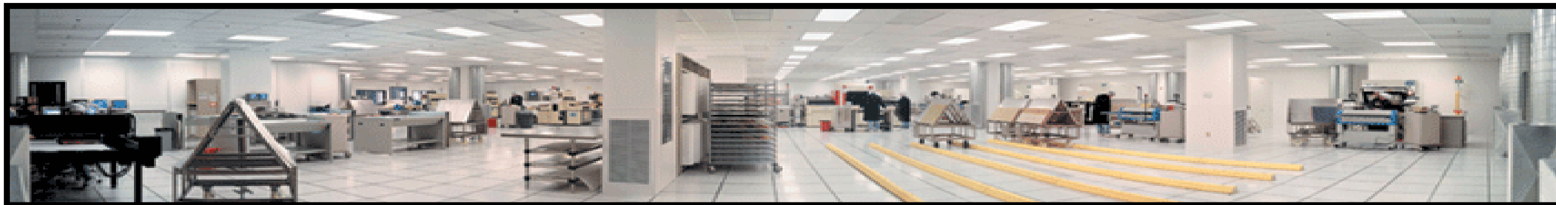


- Nashua, New Hampshire
- 214,000 square feet
  - Manufacturing 182,000 sq ft
    - Test 7,000 sq ft
    - QC 8,000 sq ft
- Continuous operation since 1978
- Certifications:
  - ISO 9001:2000
  - AS9100
  - ISO 14001:1996
  - MIL-PRF-31032/1A, /2
  - MIL-P-55110
  - MIL-P-50884 Types 1-V
  - ITAR Registered
  - IPC-A-600 – Class I, II, III
  - IPC-6012 – Class I, II, III
  - IPC-6013 – Class I, II, III



14,000 square foot, Class 10,000 clean room

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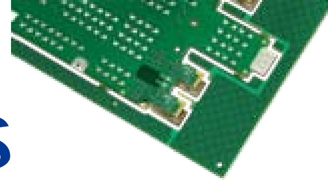

Understanding Our Market and Customers

Naval Systems 10%

Ground Systems 25%

Mil Avionics 35%

C4I 20%

Commercial Aircraft 5%

Space 5%

Suppliers are recognized by the customers they have.

Raytheon
BAE SYSTEMS
LOCKHEED MARTIN
NORTHROP GRUMMAN
CISCO
GENERAL DYNAMICS
NORTEL
Rockwell
Electronic Controls and Communications
TEXTRON
ViaSat
smiths
GOODRICH
IAI
ISRAEL AIRCRAFT INDUSTRIES ltd
BOEING
Honeywell

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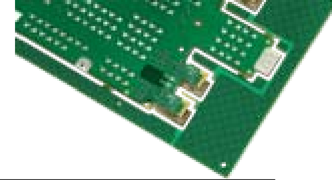
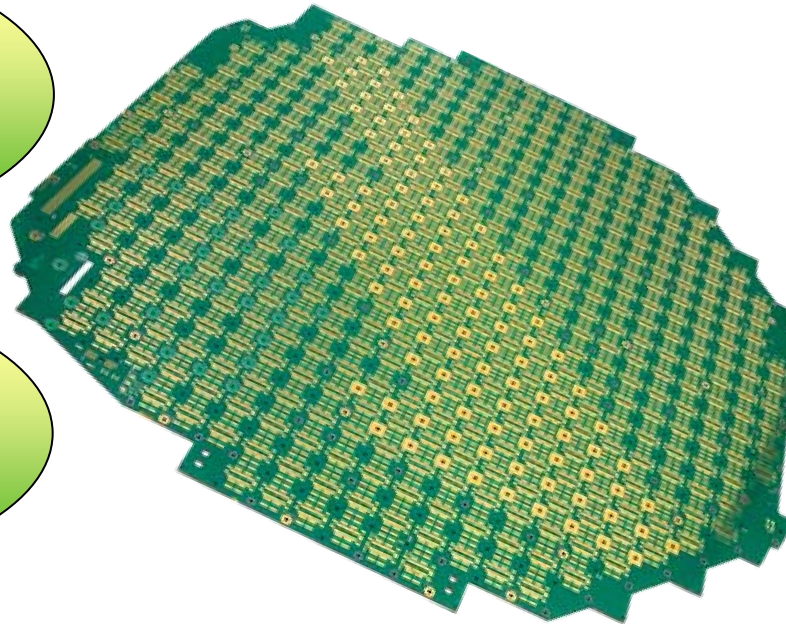
Printed Circuit Capabilities



Unique Panel Sizes
24” x 54”
30” x 44”
36 x 42”

Interconnects
Blind & Burried
Back Drilling
Depth Drilling
Laser

Materials
Polyimide
RF
Nelco
High & Low Tg



Assembly Options
Low Cost ITAR Compliant
Mexico Assembly
Facility

Assembly Options
Flex Assemblies
Through Hole
Wave
SMT
Potting
Conformal Coating
Full Testing

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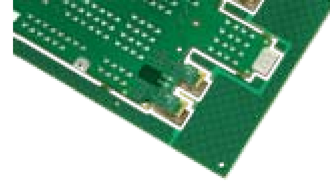
New Products



RF – With $1,000,000 invested in 2009 APC has installed Gold/Nickel plating as well as high temperature presses to accommodate RF needs

Lamination

Over Sized Flex

- Rigid and Multi-layer flex being processed on 54” long panels
- Circuit Sizes at this point are 28” x 54”
- Processing Polyimide and LCP

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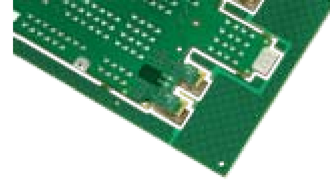
Technology Roadmap



<table>
<tr><td colspan="2"></td><td colspan="4">Technology Roadmap</td></tr>
<tr><td colspan="2"></td><td>6 Months</td><td>1 Year</td><td>2 years</td><td>5 Years</td></tr>
<tr><td rowspan="9">Products</td><td rowspan="3">RF</td><td>High Speed RF Boards</td><td></td><td colspan="2"></td></tr>
<tr><td colspan="2">High Layer Count RF Boards</td><td colspan="2"></td></tr>
<tr><td></td><td colspan="3">High Speed Material Development</td></tr>
<tr><td rowspan="2">High Temp Flex</td><td>High Temp 300°c</td><td colspan="3"></td></tr>
<tr><td></td><td colspan="3">Extreme High Temp 400°c</td></tr>
<tr><td rowspan="4">HDI</td><td>HDI Overview</td><td colspan="3"></td></tr>
<tr><td colspan="2">High density BGA's</td><td colspan="2"></td></tr>
<tr><td></td><td colspan="3">Chip on Board & Micro BGA Patterns</td></tr>
<tr><td></td><td colspan="3">High Speed Low Loss Signal</td></tr>
<tr><td rowspan="7">Materials</td><td rowspan="4">Rigid Laminates</td><td colspan="4">Low Cost FR408 Asian & HR</td></tr>
<tr><td colspan="4">High Speed Rogers 3000 & 6000; Taconic TLG29 & 30</td></tr>
<tr><td colspan="2">Cisco, HP & Nortel Qual Megtron 6 & 4 & IS 680</td><td colspan="2"></td></tr>
<tr><td></td><td colspan="3">Sputtered Copper</td></tr>
<tr><td rowspan="3">Flex Laminates</td><td colspan="2">LCP - Rogers Processing</td><td colspan="2"></td></tr>
<tr><td></td><td colspan="2">DuPont High Speed High Temp Processing</td><td></td></tr>
<tr><td colspan="2"></td><td colspan="2">Off Shore Low Cost Materials</td></tr>
<tr><td rowspan="9">Methods</td><td rowspan="9">Processes</td><td>Lamination Upgrade</td><td colspan="3"></td></tr>
<tr><td colspan="3">Enhance Layer & Sub Registration XACT PCB Reg Software</td><td></td></tr>
<tr><td colspan="2">Thin Cu Processing - ≥1/4 oz</td><td colspan="2"></td></tr>
<tr><td></td><td>Via Fill In-House</td><td colspan="2"></td></tr>
<tr><td>ENIG</td><td></td><td colspan="2"></td></tr>
<tr><td colspan="2">High Speed Test Capabilities</td><td colspan="2"></td></tr>
<tr><td colspan="2"></td><td colspan="2">Additional Flying Probe Capacity/Capability</td></tr>
<tr><td colspan="2">Automated Wave Soldering</td><td colspan="2"></td></tr>
<tr><td colspan="2">Automated Conformal Coating</td><td colspan="2"></td></tr>
<tr><td colspan="6">Space and weight continue to drive packaging smaller while adding more features, High Speed materials and technologies such as RF and HDI allows us to participate on the next generation of printed circuit interconnects</td></tr>
<tr><td colspan="6">ENIG and Via Fill in house capabilities decrease turn times and increase cost competitiveness</td></tr>
<tr><td colspan="6">Working with our core material suppliers will enable us to manufacture cutting edge speeds and temperature for next generation systems</td></tr>
<tr><td colspan="6">Working with equipment that is in place in Mexico will allow us to reduce our cost and increase our yields to drive more value to our customers</td></tr>
</table>

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